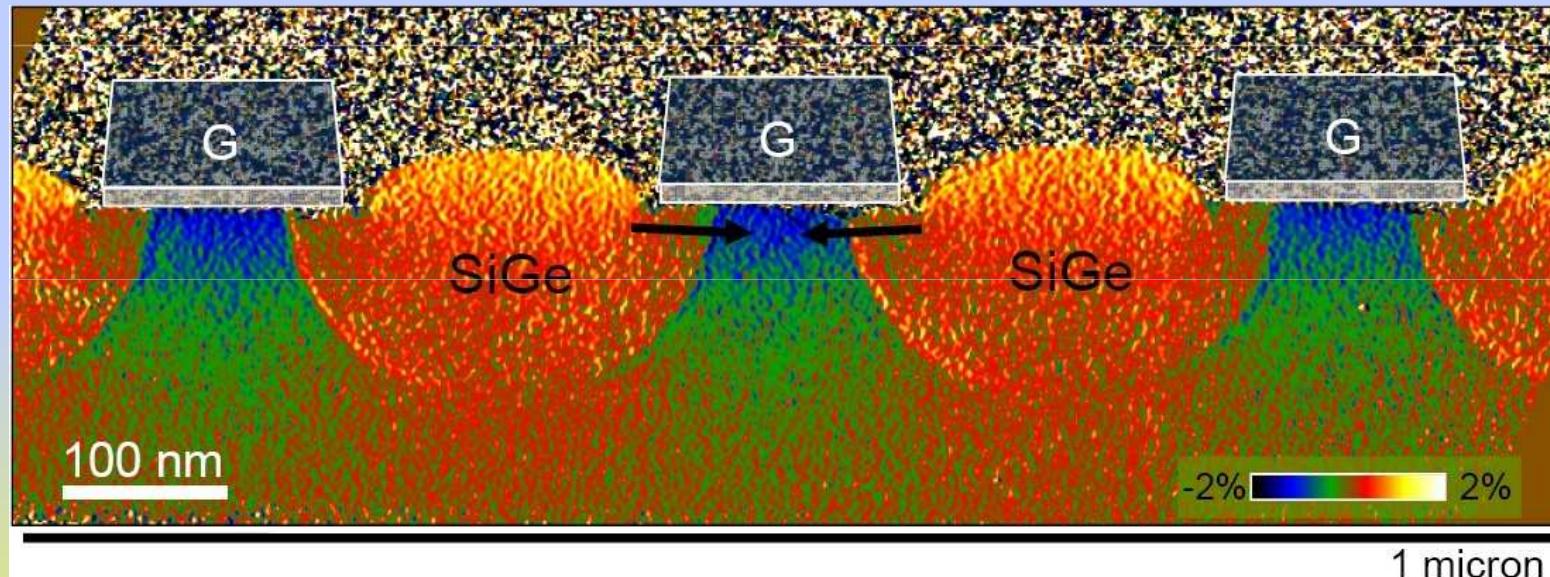


# Dark-field holography for the measurement of strain at the nanoscale



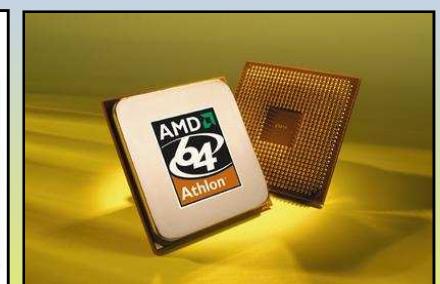
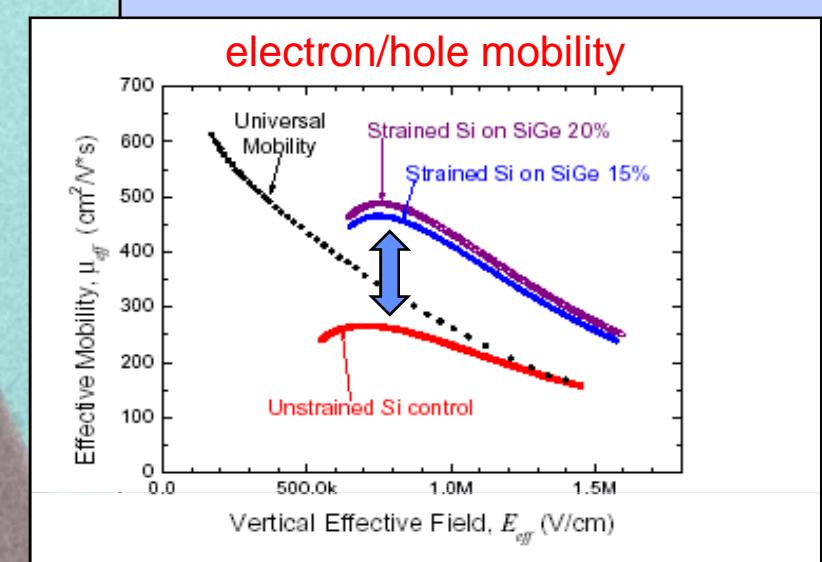
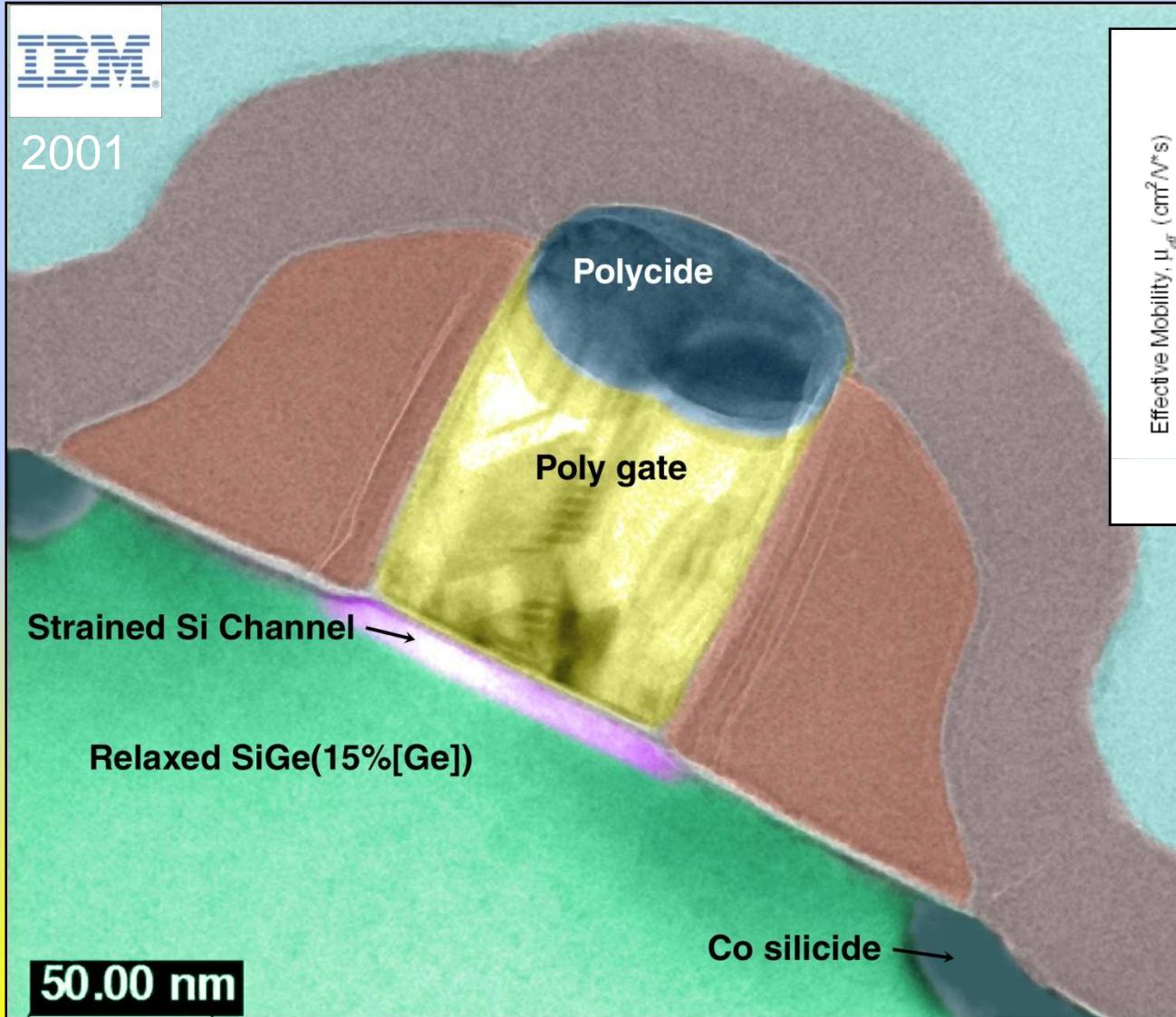
Martin Hÿtch, Florent Houdellier, Florian Hüe\*,  
Etienne Snoeck, Alain Claverie



CEMES-CNRS, nMat group ,Toulouse, France

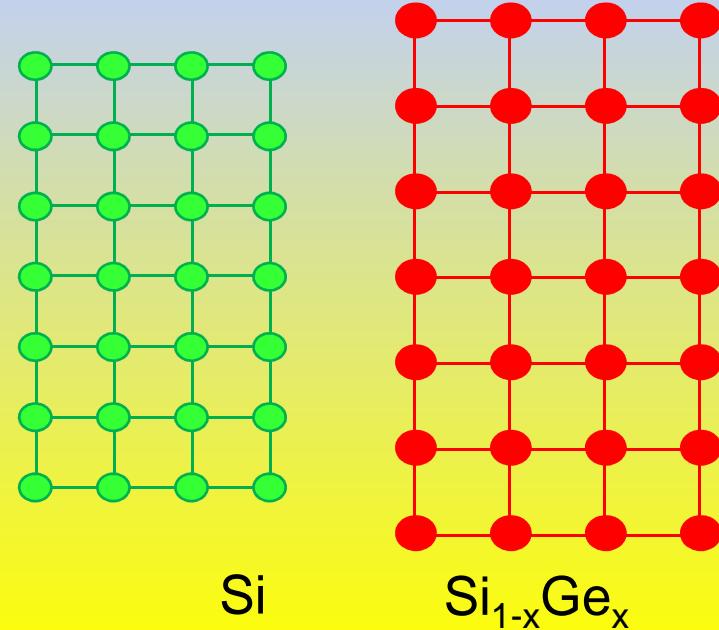
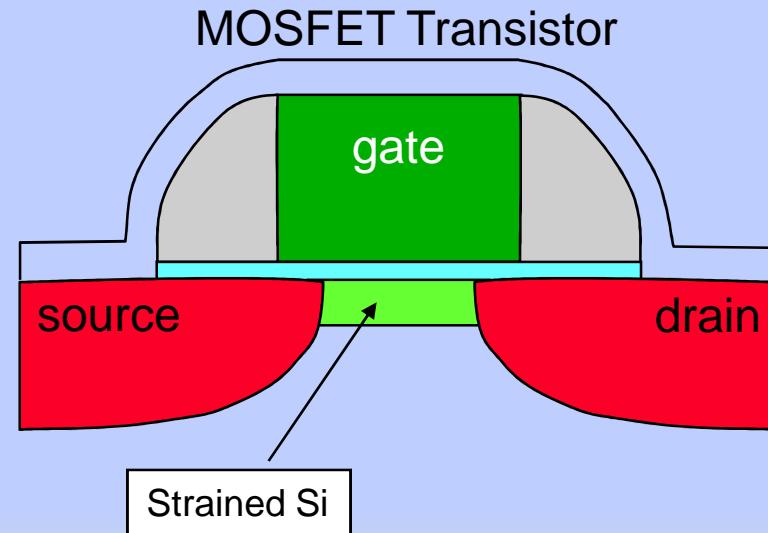
*Patent applications FR 07 06711, FR 08 01662*

# Strained silicon channel

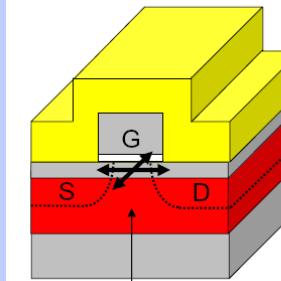


- strain increases processor speed

# Engineering strain



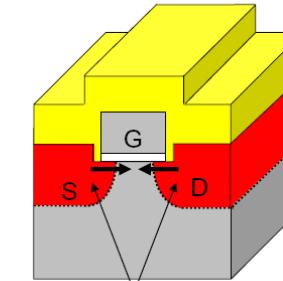
## Traditional Approach



Graded SiGe Layer

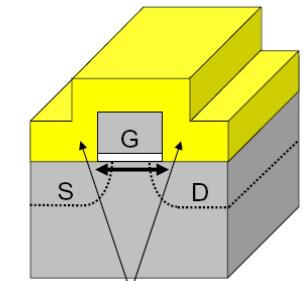
Biaxial  
Tensile Strain

## Intel's 90nm Technology



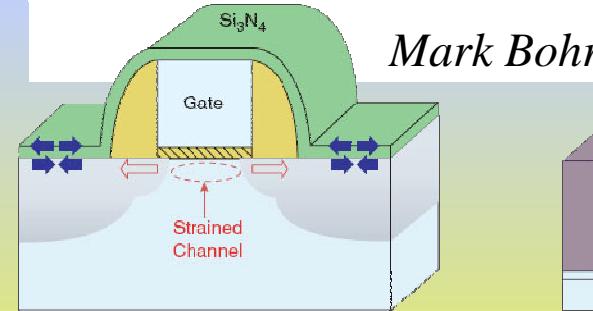
Selective SiGe S-D

Uniaxial  
Compressive Strain  
for PMOS

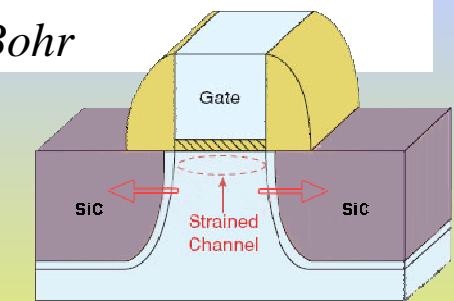


Tensile  $\text{Si}_3\text{N}_4$  Cap

Uniaxial  
Tensile Strain  
for NMOS



Mark Bohr



- need to measure strain
- complex distributions

# Geometric phase

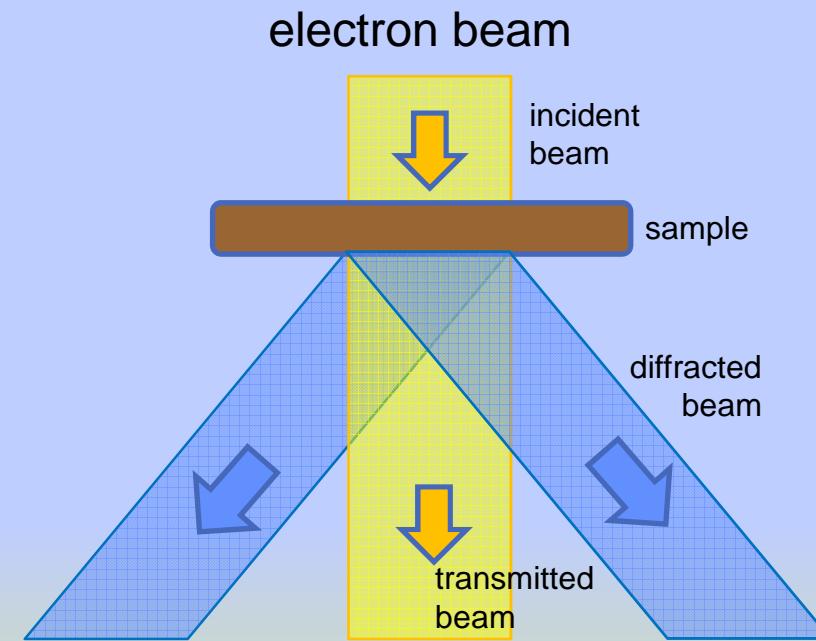
wave function

$$\psi(\mathbf{r}) = \sum_g \tilde{\psi}_g(\mathbf{r}) \exp\{2\pi i \mathbf{g} \cdot \mathbf{r}\}$$

diffracted beams

$\mathbf{r} \rightarrow \mathbf{r} - \mathbf{u}$  displacement

$$\rightarrow \tilde{\psi}_g \rightarrow \tilde{\psi}_g e^{-2\pi i \mathbf{g} \cdot \mathbf{u}}$$



geometric phase

$$\phi_g^G = -2\pi \mathbf{g} \cdot \mathbf{u}$$

displacement

$$\rightarrow \varepsilon_{ij} = \frac{1}{2} \left( \frac{\partial u_i}{\partial x_j} + \frac{\partial u_j}{\partial x_i} \right)$$

strain

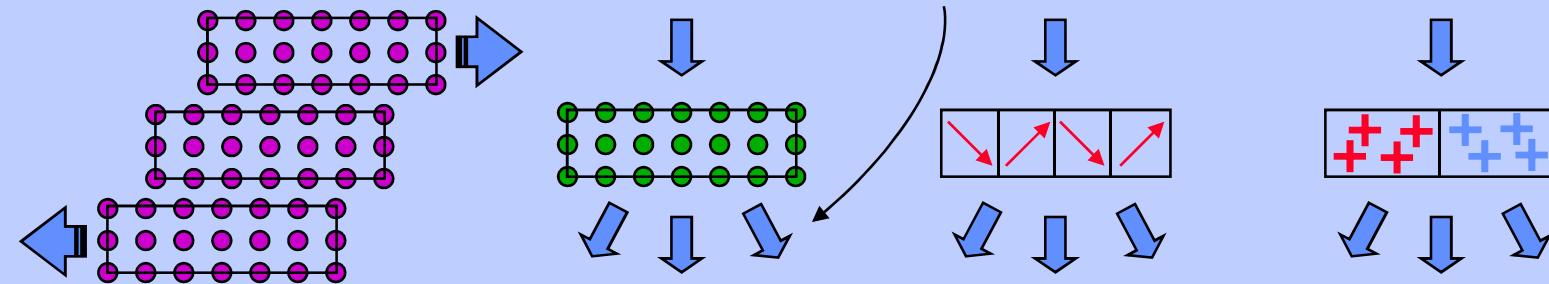
# Phase microscopy

interaction  
electron-matter

$$\psi(\mathbf{r}) = \sum_{\mathbf{g}} \tilde{\psi}_g(\mathbf{r}) e^{2\pi i \mathbf{g} \cdot \mathbf{r}}$$

↑  
amplitude and phase

Fourier  
space



phase shift

**G**  
geometric  
phase

**C**  
crystalline  
potential

**M**  
magnetic  
fields

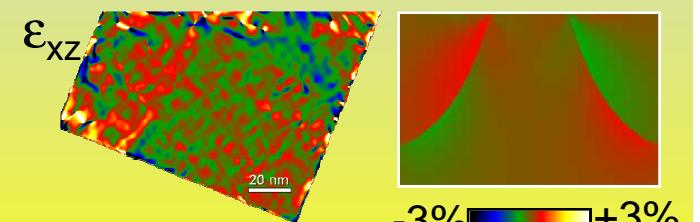
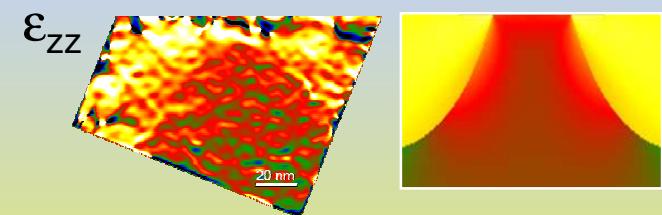
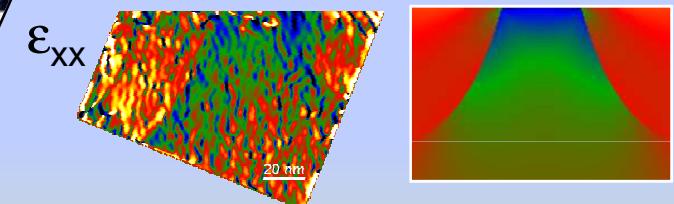
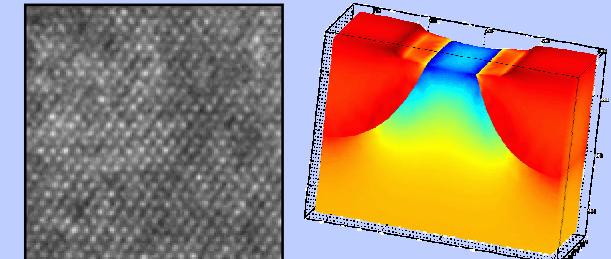
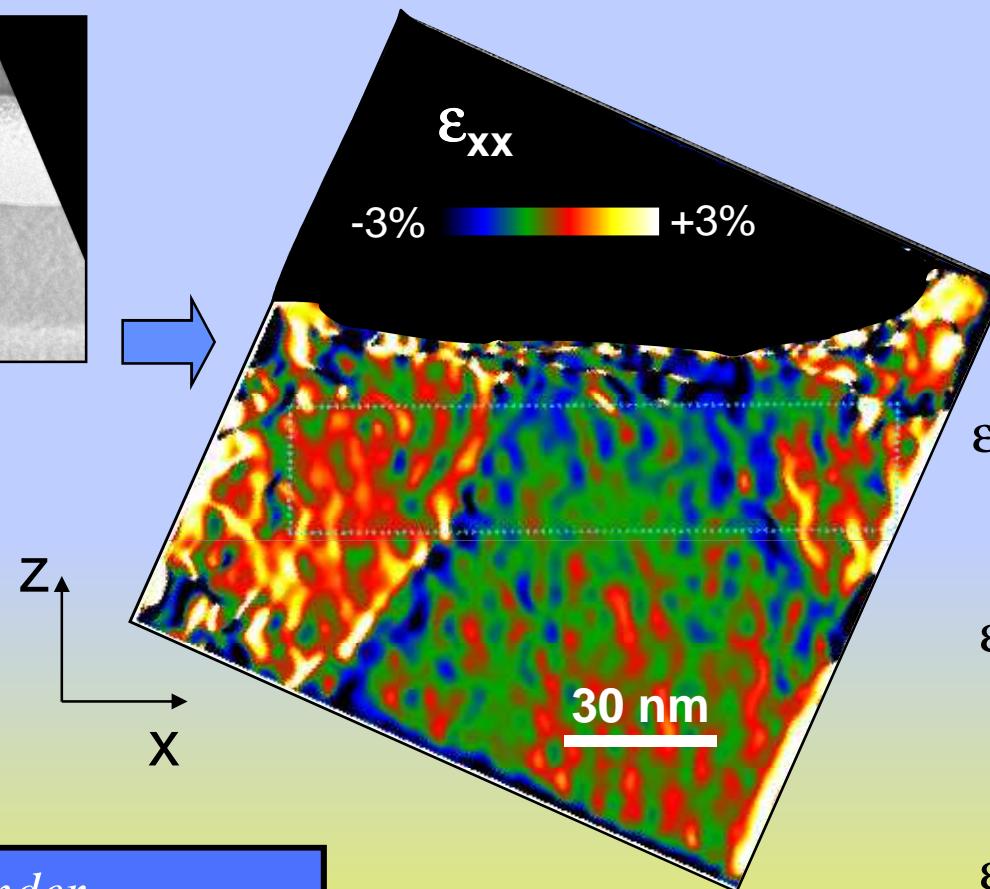
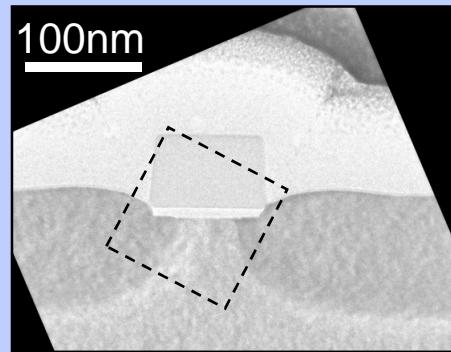
**E**  
electrostatic  
fields

$$\phi = \underbrace{\phi^G}_{\substack{\uparrow \text{HREM} \\ \text{HoloDark}}} + \underbrace{\phi^C}_{\substack{\uparrow \text{EH}}} + \underbrace{\phi^M}_{\substack{\uparrow \text{EH}}} + \underbrace{\phi^E}_{\substack{\uparrow \text{EH}}}$$

interferometry

HoloDark

# High-resolution TEM

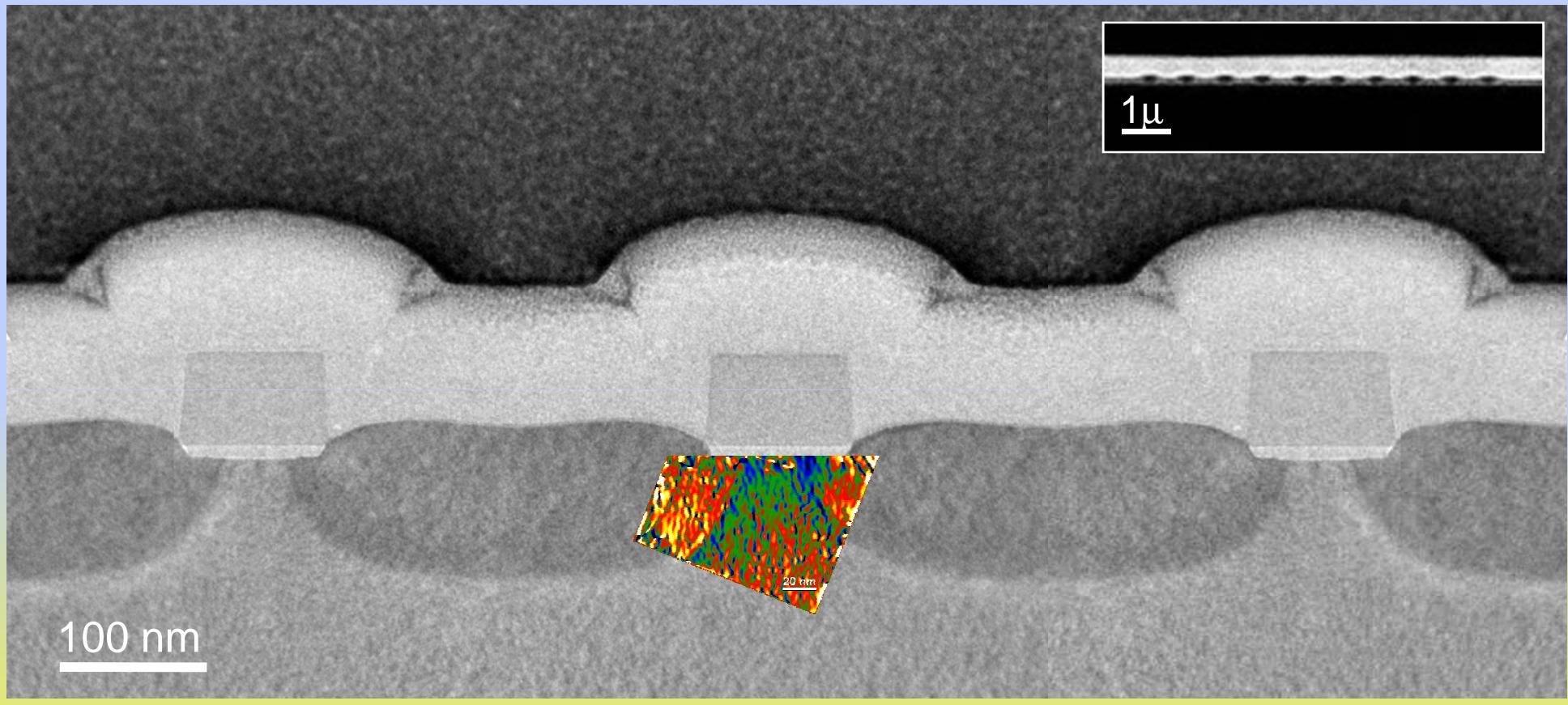


Hugo Bender  
IMEC-Leuven, Belgium

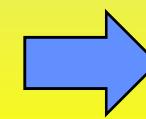


Jean-Michel Hartmann  
CEA-LETI, Grenoble, France

# Need for a new technique



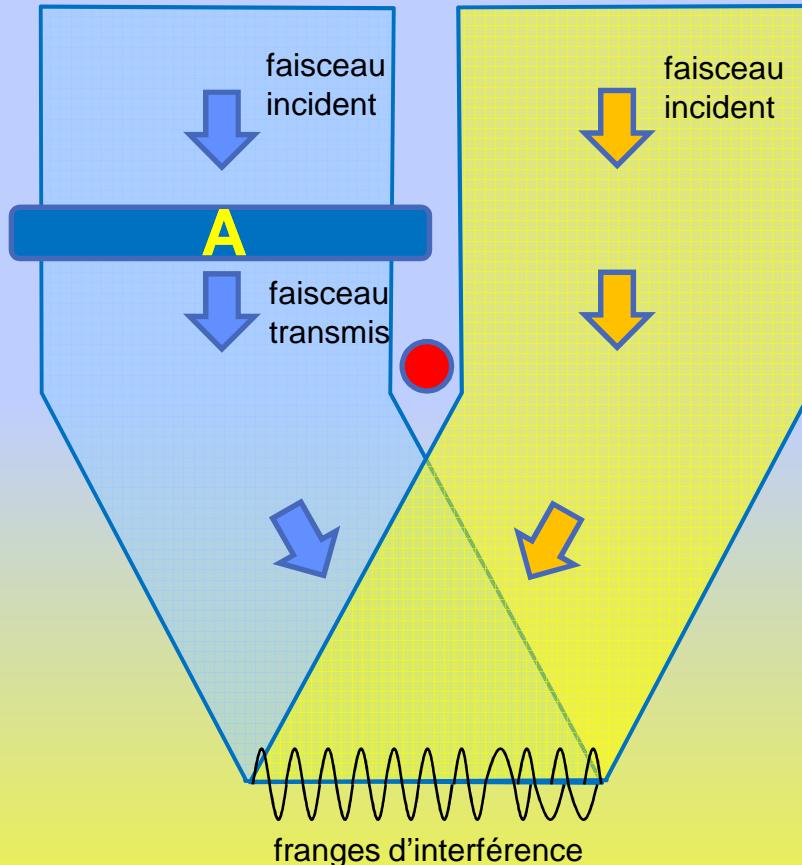
1 micron



wider field of view  
thicker crystals

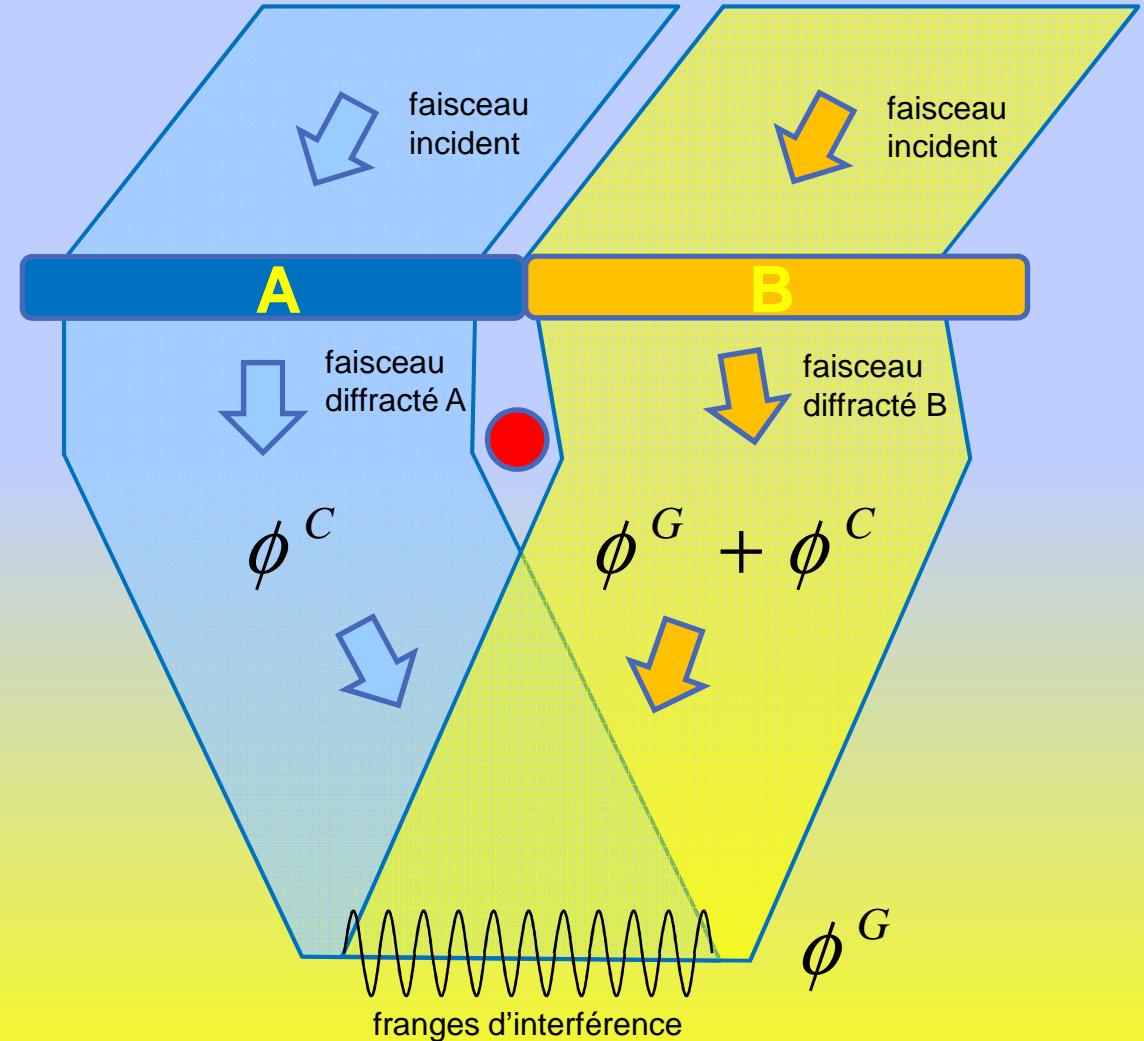
# Dark-field Holography

Conventional holography



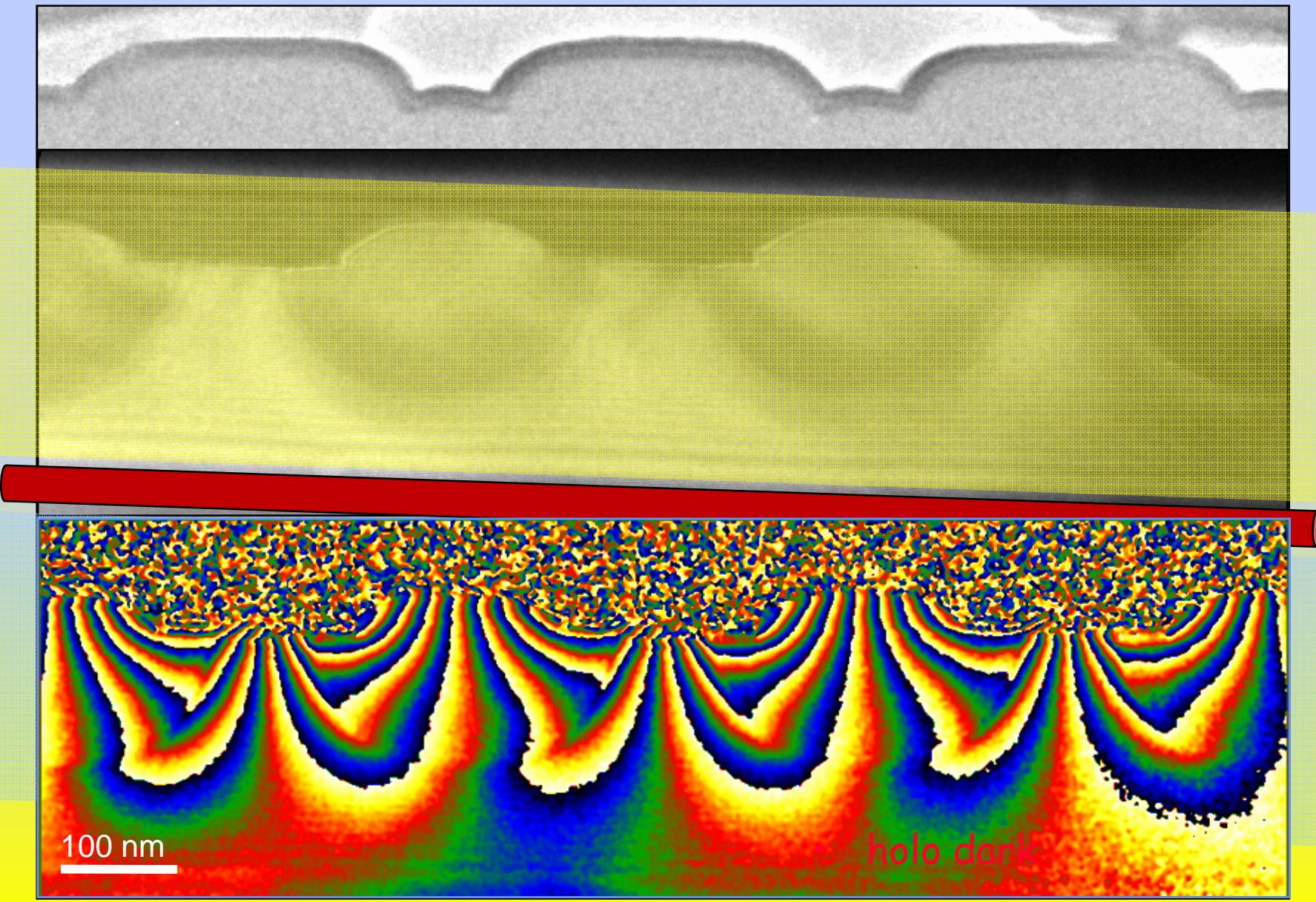
$$\phi = \phi^M + \phi^E$$

Dark-field holography

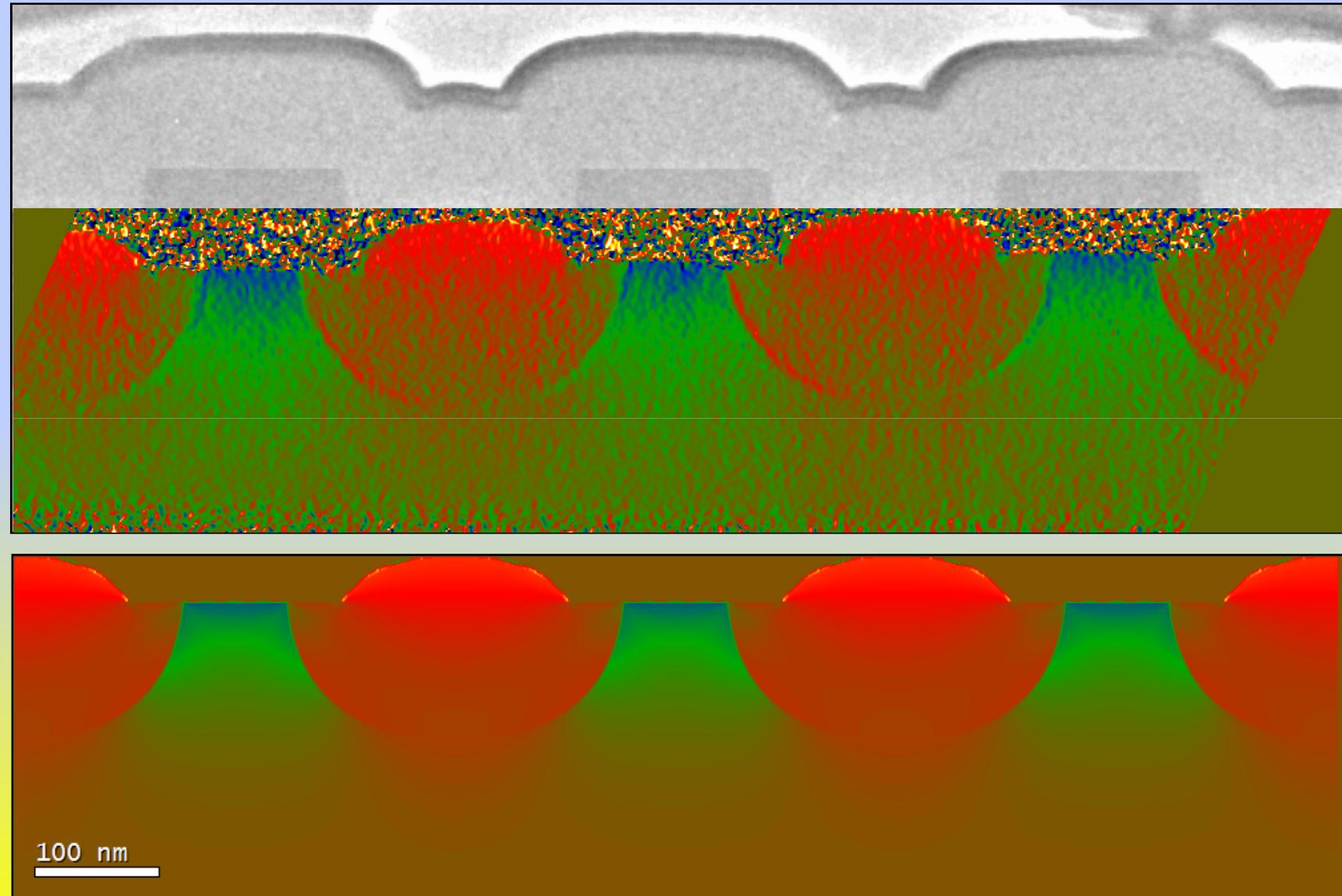


- direct measurement of geometric phase

# Experiment

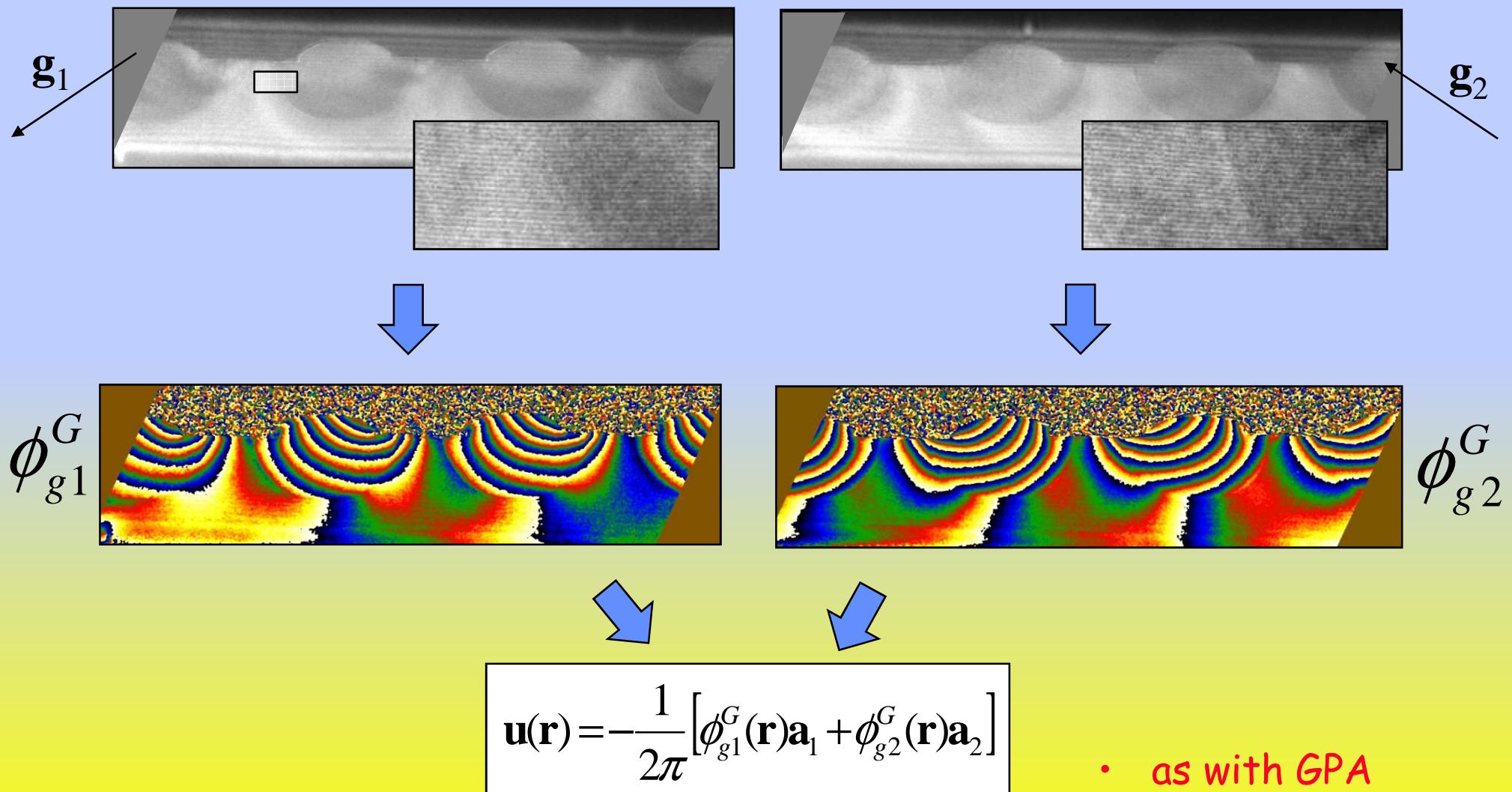


# Deformation measurement

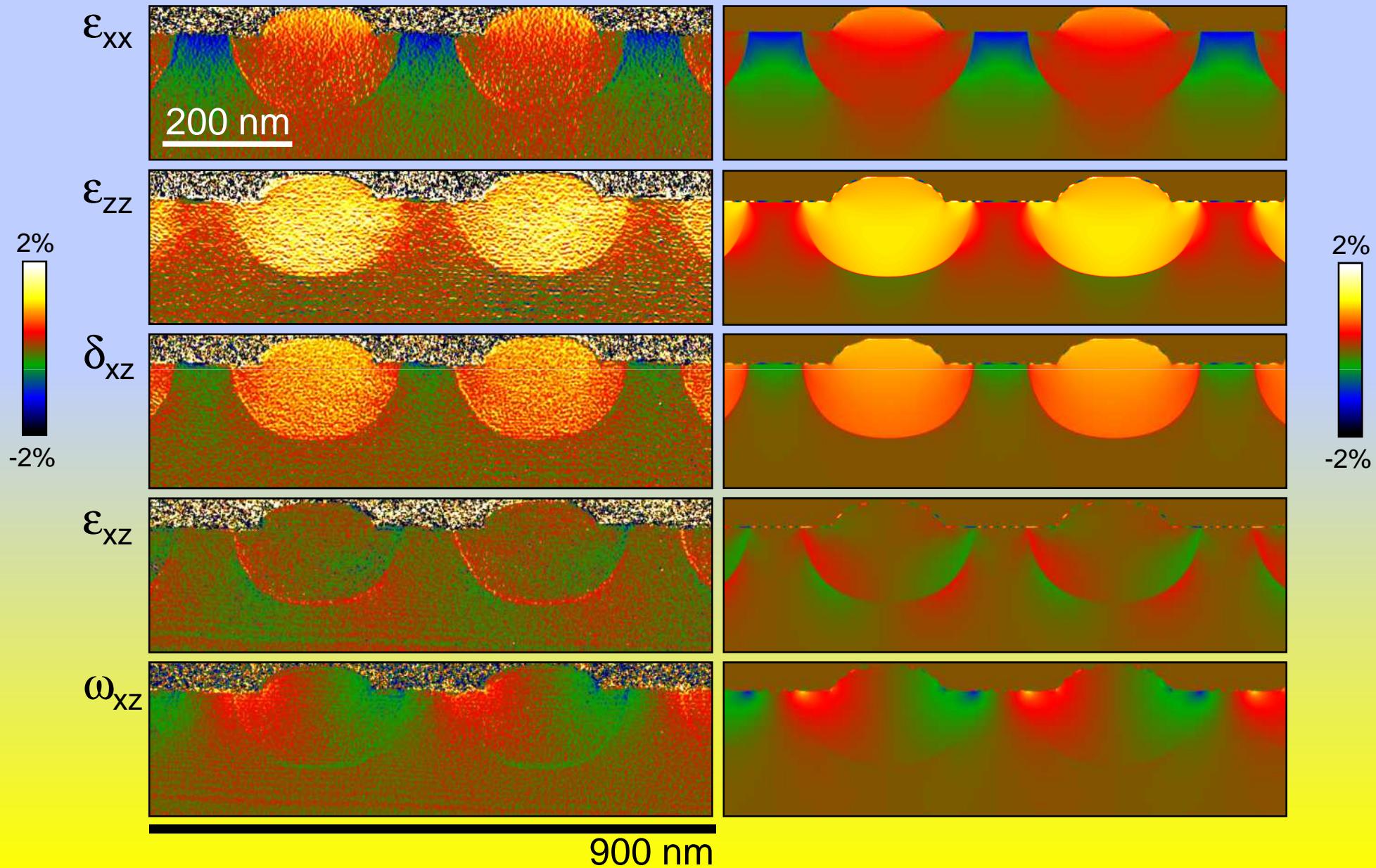


M.J. Hÿtch, F. Houdellier, F. Hüe & E. Snoeck, Nature 453 (19<sup>th</sup> June 2008) 1086

## 2D Deformation

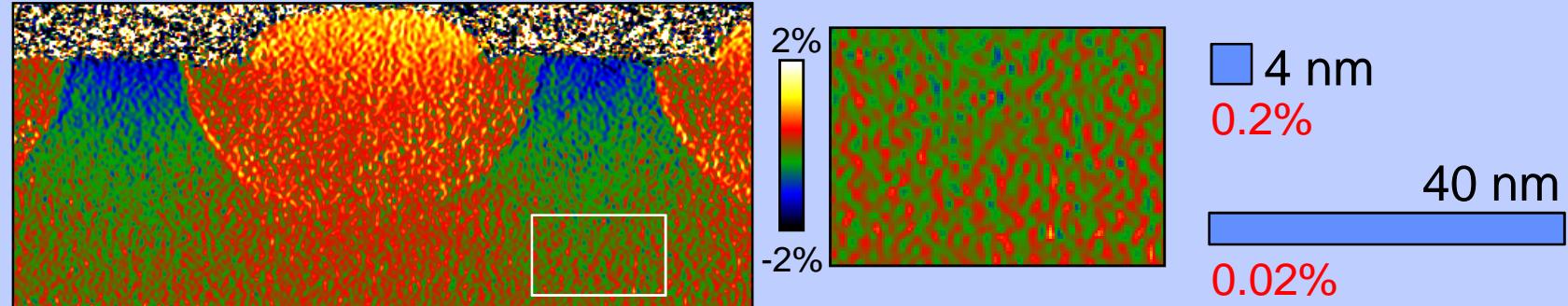


# Strain components

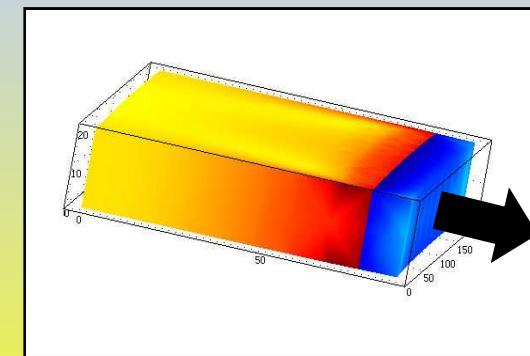
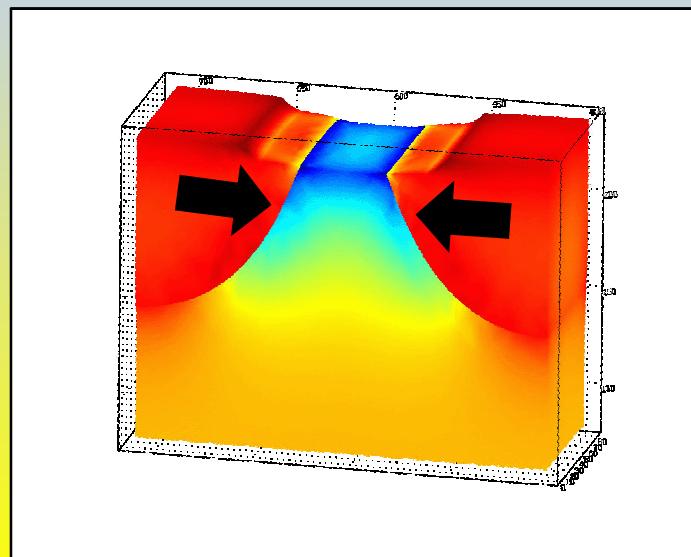


# Accuracy and precision

## Noise

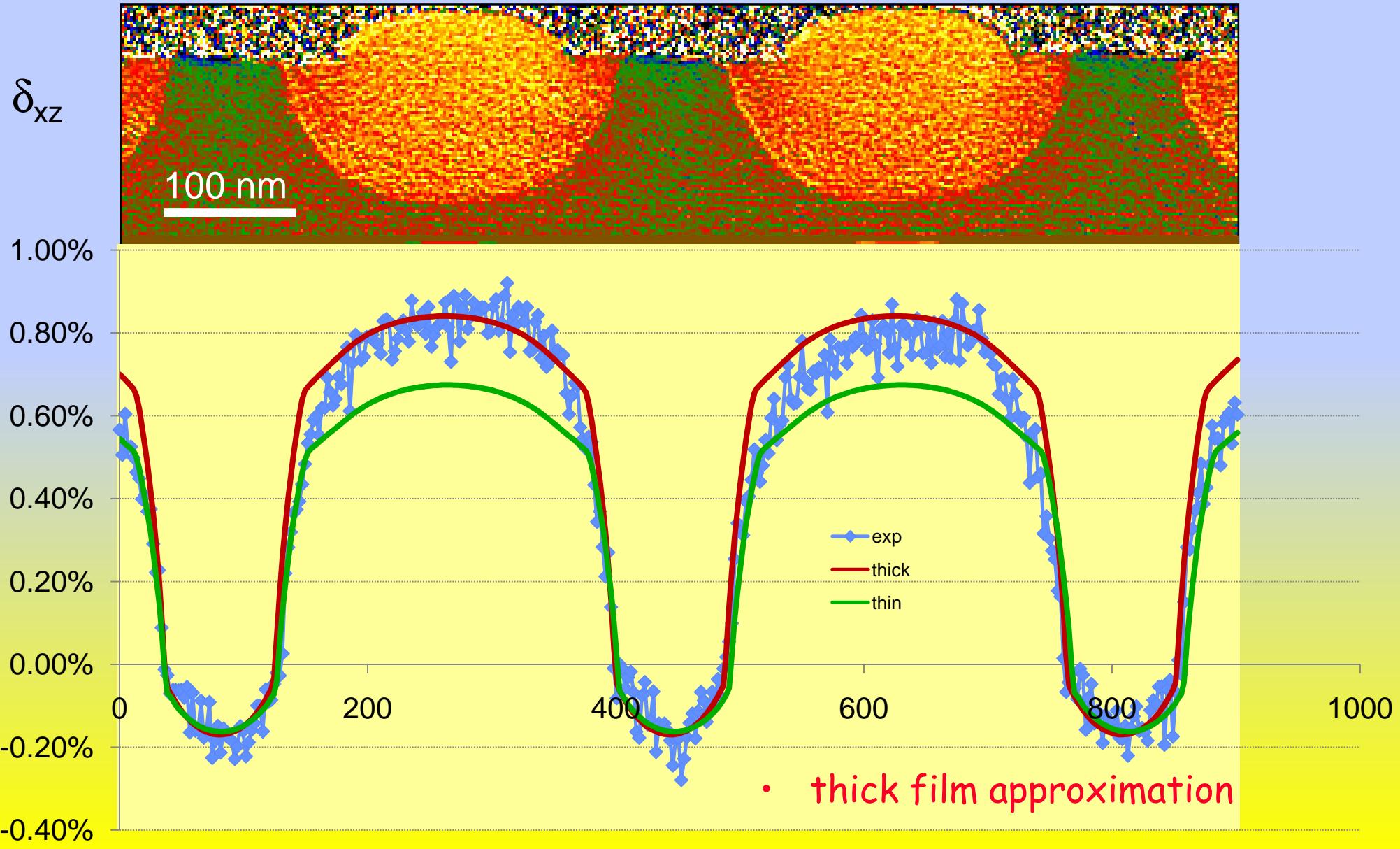


## Thin film relaxation

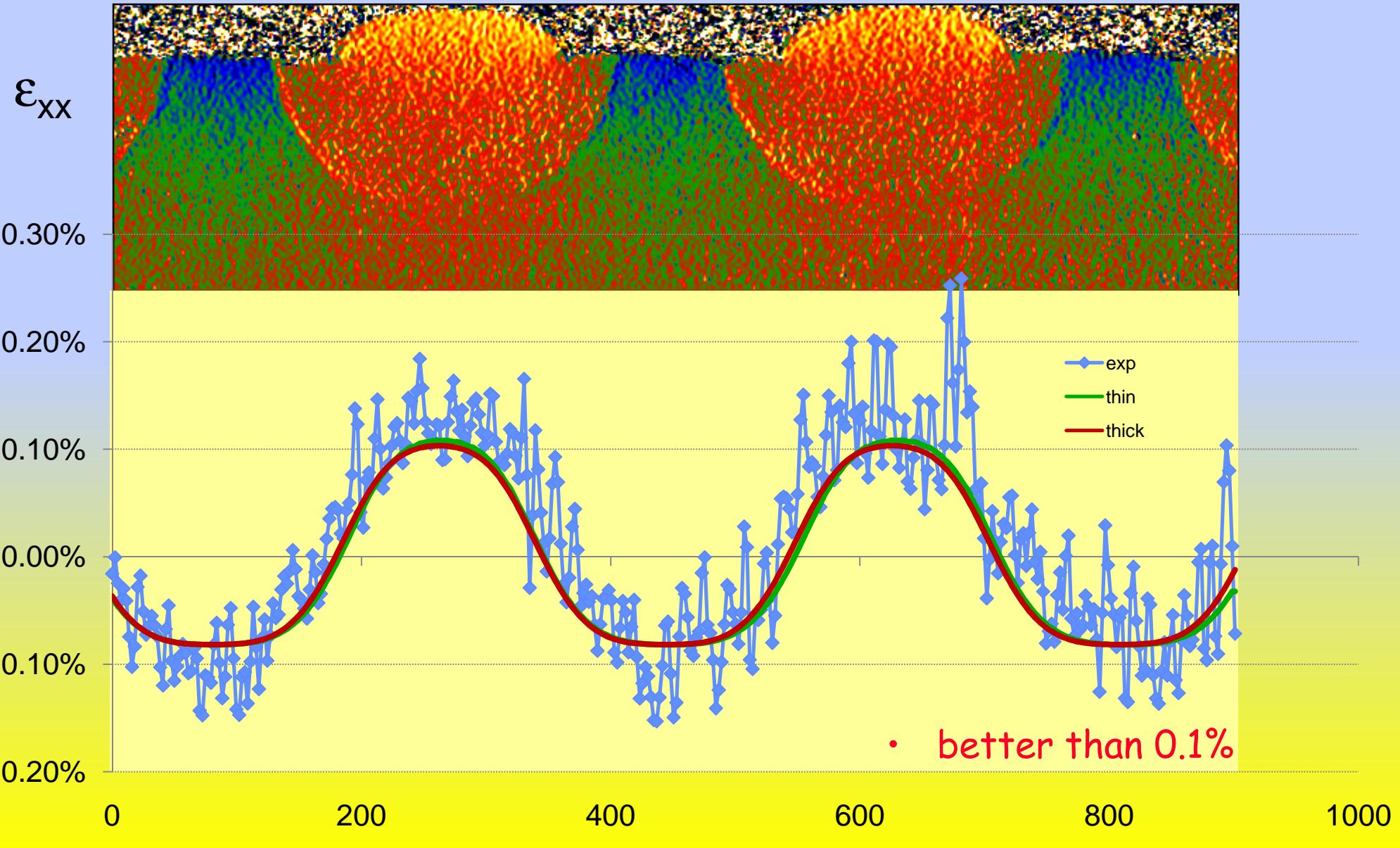


- best and worst
- aspect ratio

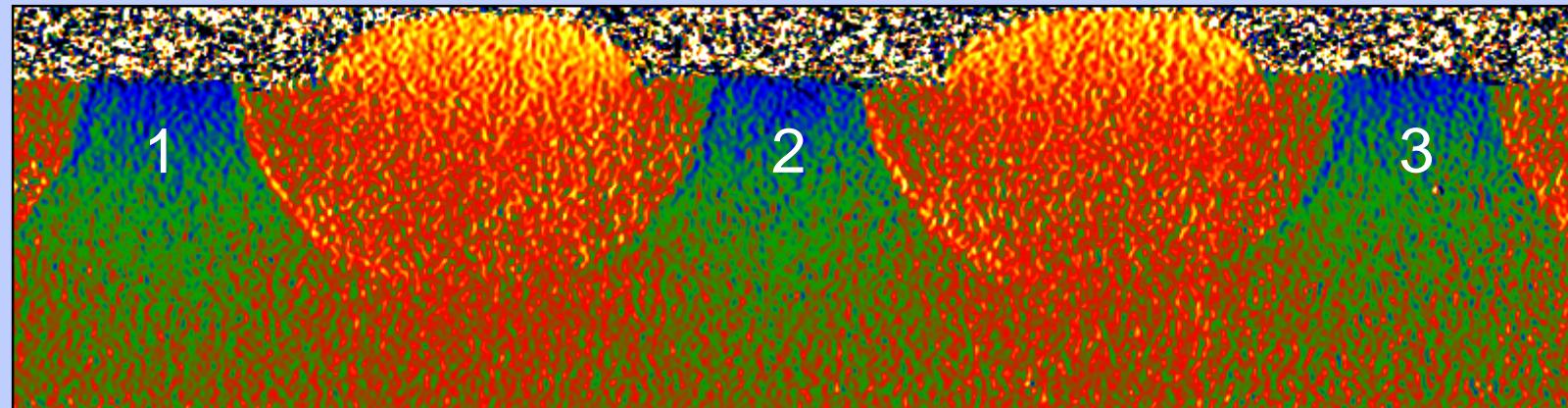
# Thick or thin ?



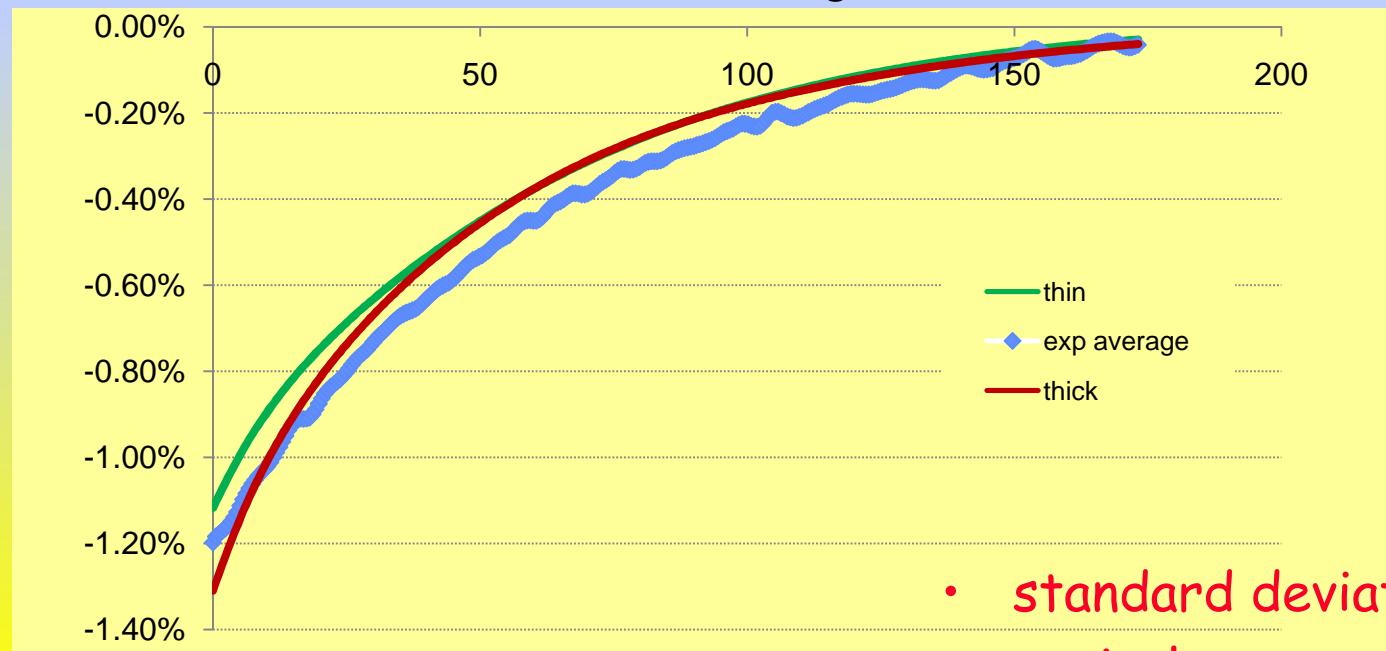
## Sensitivity



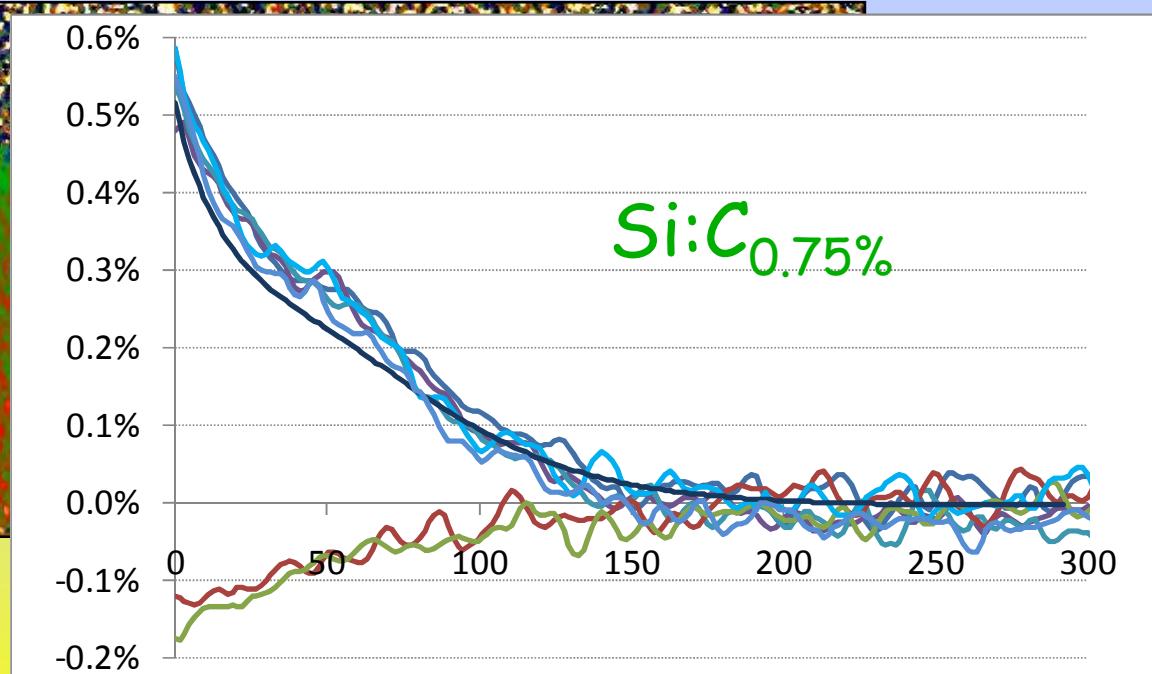
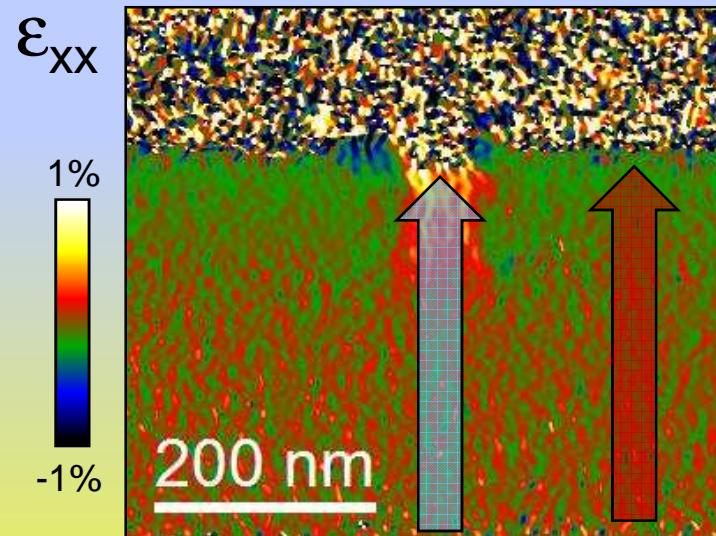
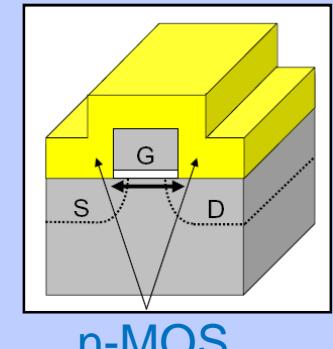
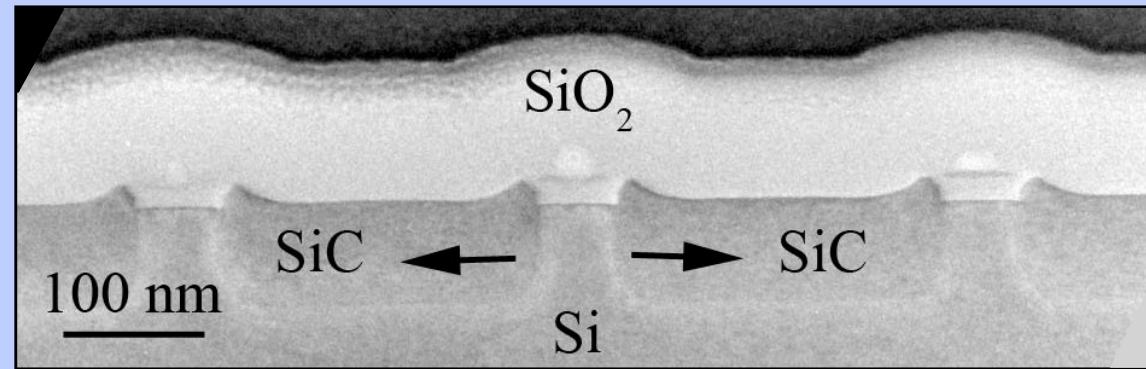
# Reproducibility

 $\varepsilon_{xx}$ 

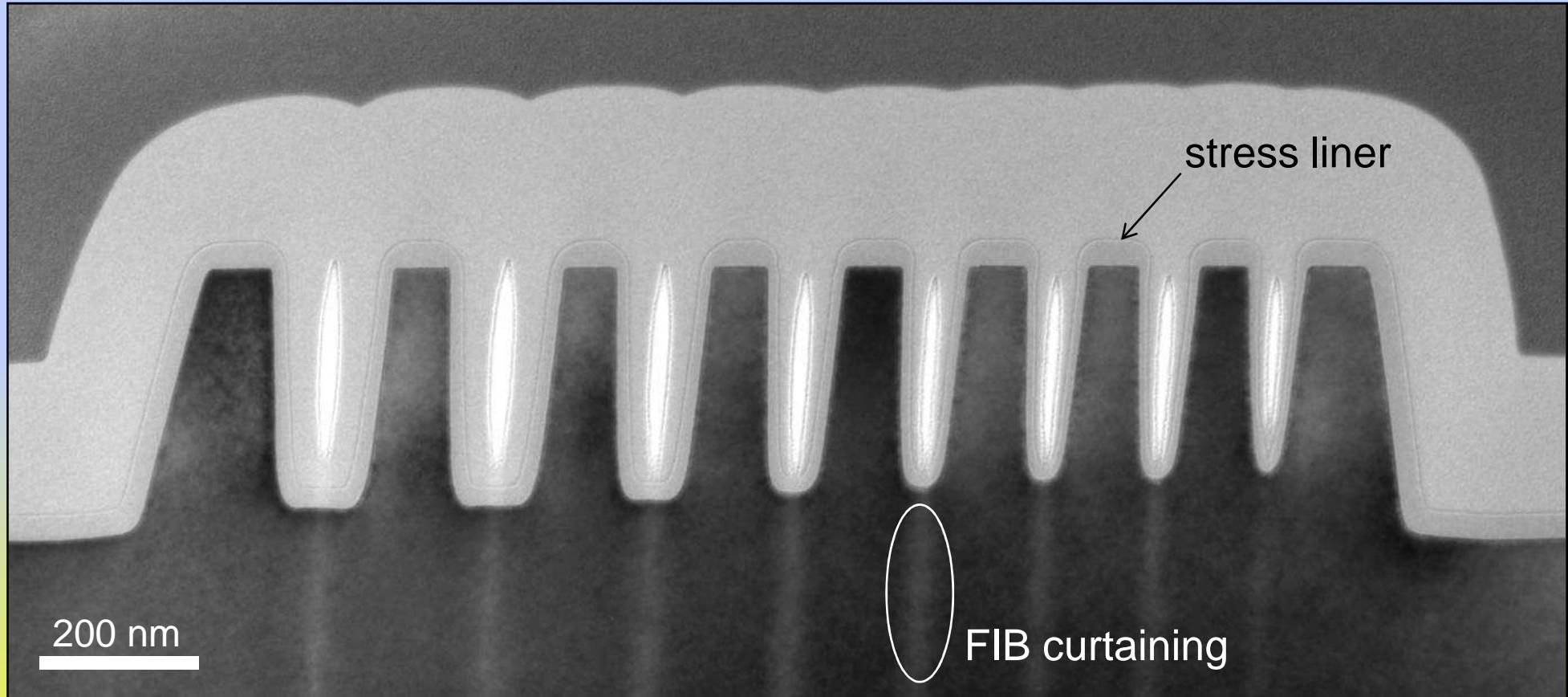
Distance from gate / nm



# nMOSFET with Si:C<sub>1%</sub>



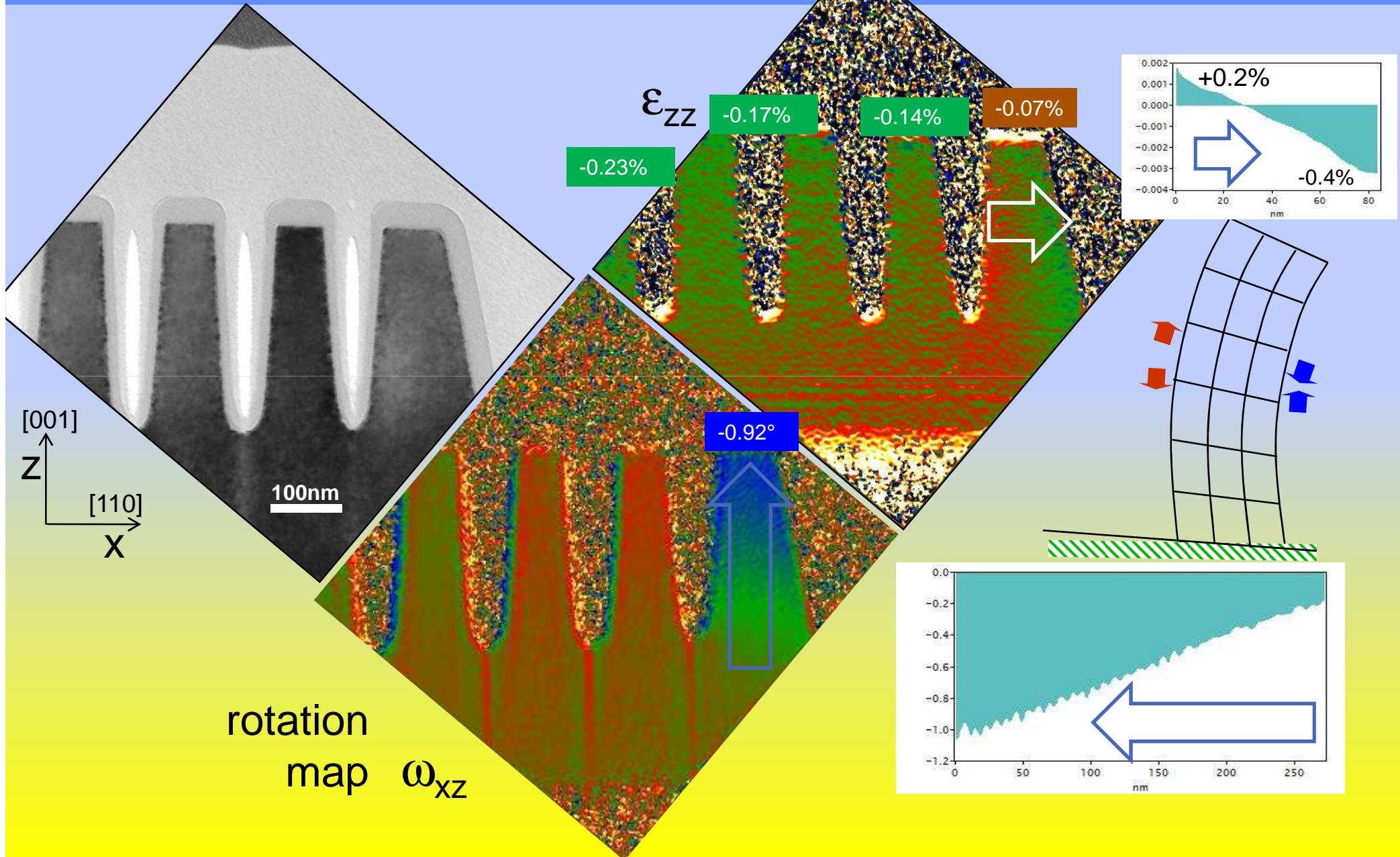
# Flash memory test structure



Aomar Halimaoui  
Laurent Clément  
Pierre Morin

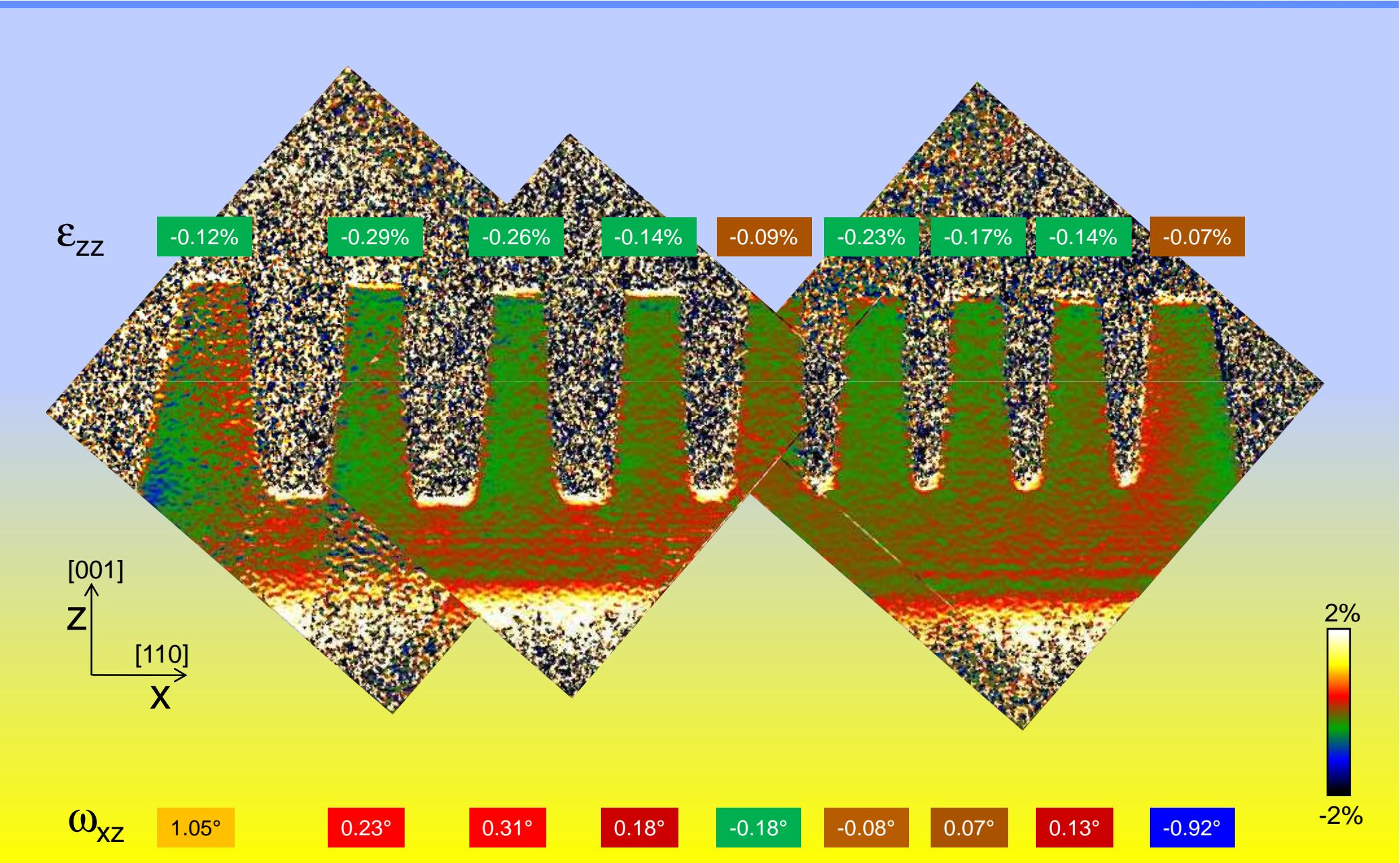
- CESL applies stress

# Bending

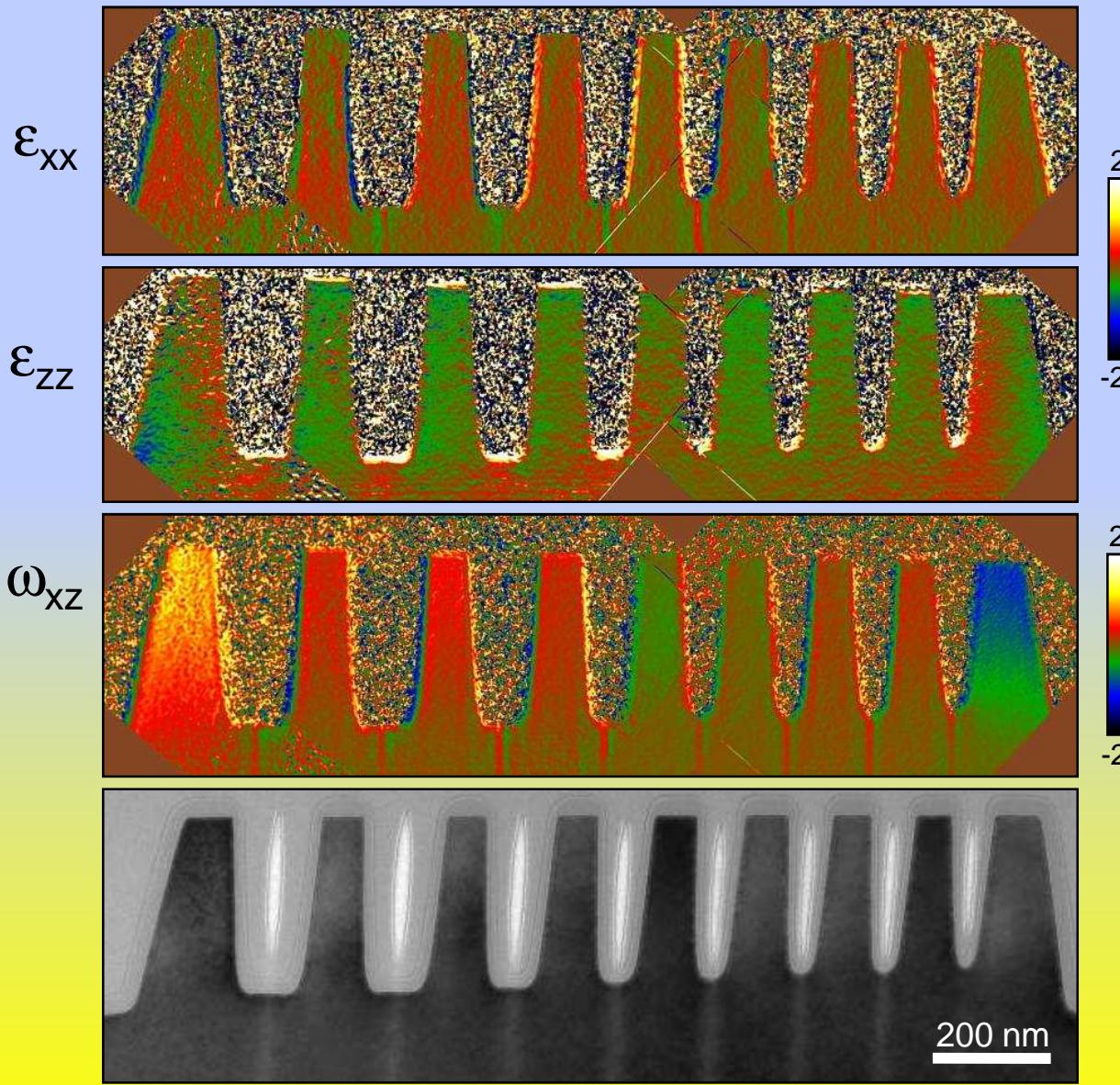


Rotation,  $\omega_{xz}$ 

# Vertical strains, $\varepsilon_{zz}$



# Summary of CESL results



$\epsilon_{xx}, \epsilon_{xz} = 0.00\%-0.09\%$

$\epsilon_{zz} = -0.19\% \pm 0.07\%$

$\omega_{xz} = 0.1^\circ, \pm 1^\circ$



$\sigma_{zz} = -300 \text{ MPa} \pm 100 \text{ MPa}$

# Requirements and Summary

- large fields of view
- thick crystals
- high precision
- high success rate
- easier than HREM ?

- equipment
- software
- microscopist

- thickness
- composition
- crystal bending



- dedicated equipment

FIB specimen

Lorentz lens

biprism

CCD

